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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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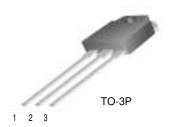
## FFA20U120DN

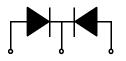
### **Features**

- · High voltage and high reliability
- · High speed switching
- Low forward voltage

## **Applications**

- General purpose
- Switching mode power supply
- Free-wheeling diode for motor application
- · Power switching circuits





1. Anode 2. Cathode 3. Anode

## **ULTRA FAST RECOVERY POWER RECTIFIER**

## Absolute Maximum Ratings (per diode) T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>RRM</sub>	Peak Repetitive Reverse Voltage	1200	V
I <sub>F(AV)</sub>	Average Rectified Forward Current @T <sub>C</sub> = 100°C	20	Α
I <sub>FSM</sub>	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	120	Α
T <sub>J,</sub> T <sub>STG</sub>	Operating Junction and Storage Temperature	- 65 to +150	°C

## **Thermal Characteristics**

Symbol		Parameter	Value	Units	
	R <sub>e,IC</sub>	Maximum Thermal Resistance, Junction to Case	0.84	°C/W	

## Electrical Characteristics (per diode) T<sub>C</sub>=25 °C unless otherwise noted

Symbol	Parameter		Min.	Тур.	Max.	Units
V <sub>FM</sub> *	Maximum Instantaneous Forward Voltage					V
	$I_F = 20A$	T <sub>C</sub> = 25 °C T <sub>C</sub> = 100 °C	-	-	3.5	
	I <sub>F</sub> = 20A	$T_C = 100  ^{\circ}C$	-	-	3.2	
RM *	Maximum Instantaneous Reverse Current					
	@ rated V <sub>R</sub>	$T_C = 25  ^{\circ}C$	-	-	20	μΑ
		$T_C = 25  ^{\circ}C$ $T_C = 100  ^{\circ}C$	-	-	1.2	mA
rr	Maximum Reverse Recovery Time		-	-	120	ns
rr	Maximum Reverse Recovery Current		-	-	10	Α
Q <sub>rr</sub>	Maximum Reverse Recovery Charge (I <sub>F</sub> =20A, di/dt = 200A/μs)		-	-	500	nC
N <sub>AVL</sub>	Avalanche Energy		1.0	-	-	mJ

<sup>\*</sup> Pulse Test: Pulse Width=300μs, Duty Cycle=2%

## **Typical Characteristics**

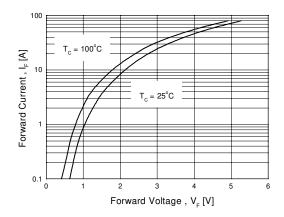


Figure 1. Typical Forward Voltage Drop vs. Forward Current

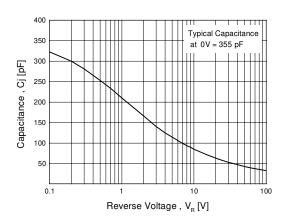


Figure 3. Typical Junction Capacitance

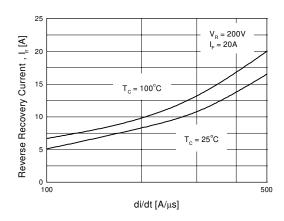


Figure 5. Typical Reverse Recovery Current vs. di/dt

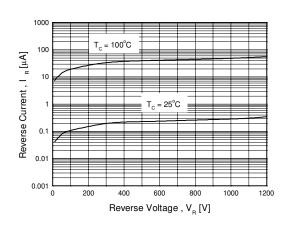


Figure 2. Typical Reverse Current vs. Reverse Voltage

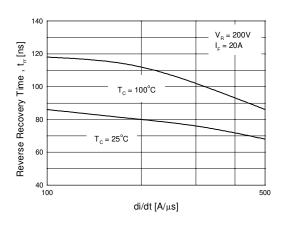


Figure 4. Typical Reverse Recovery Time vs. di/dt

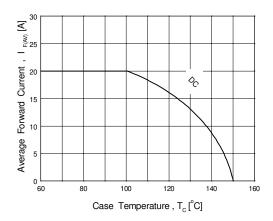
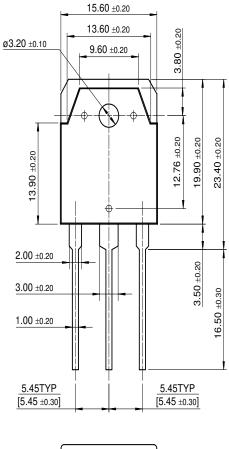
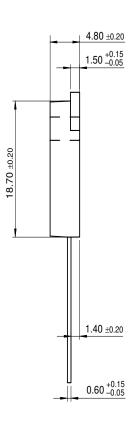


Figure 6. Forward Current Derating Curve

## **Package Dimensions**

# TO-3P





Dimensions in Millimeters

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